


<b>PCN Number:</b>	20190318003.1		<b>PCN Date:</b>	Mar 19, 2019												
<b>Title:</b>	Qualification of ASES as Additional Assembly and Test Site for Select SOIC Package Devices															
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services													
<b>Proposed 1<sup>st</sup> Ship Date:</b>	June 19, 2019	<b>Estimated Sample Availability:</b>	Date Provided at Sample request													
<b>Change Type:</b>																
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site											
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material											
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process											
<input type="checkbox"/>	Mechanical Specification	<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site											
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials											
		<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process											
<b>PCN Details</b>																
<b>Description of Change:</b>																
Texas Instruments Incorporated is announcing the qualification ASES as Additional Assembly and Test Site for select devices listed in the "Product Affected" Section. Current assembly sites and Material differences are as follows.																
<table border="1"> <thead> <tr> <th>Assembly Site</th> <th>Assembly Site Origin</th> <th>Assembly Country Code</th> <th>Assembly Site City</th> </tr> </thead> <tbody> <tr> <td>TI Malaysia</td> <td>MLA</td> <td>MYS</td> <td>Kuala Lumpur</td> </tr> <tr> <td><b>ASES</b></td> <td><b>ASH</b></td> <td><b>CHN</b></td> <td><b>Shanghai</b></td> </tr> </tbody> </table>					Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City	TI Malaysia	MLA	MYS	Kuala Lumpur	<b>ASES</b>	<b>ASH</b>	<b>CHN</b>	<b>Shanghai</b>
Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City													
TI Malaysia	MLA	MYS	Kuala Lumpur													
<b>ASES</b>	<b>ASH</b>	<b>CHN</b>	<b>Shanghai</b>													
<b>Material Differences:</b>																
	<b>TI Malaysia</b>	<b>ASES</b>														
Mount Compound	4147858	EY1000063														
Mold compound	4211880	EN2000509														
Lead finish	NiPdAu	Matte Sn														
<p>Upon expiration of this PCN, TI will combine lead free solutions in a single <b><u>standard part number</u></b>, for example; <b><u>TMP1075DR</u></b> – can ship with both Matte Sn and NiPdAu. When available customers may specify NiPdAu finish by ordering the part with the G4 suffix, e.g. <b><u>TMP1075DRG4.</u></b>"</p> <p>Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.</p>																
<b>Reason for Change:</b>																
Continuity of supply.																
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>																
None																
<b>Anticipated impact on Material Declaration</b>																
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the <a href="#">TI Eco-Info website</a> . There is no impact to the material meeting current regulatory compliance requirements with this PCN change.													
<b>Changes to product identification resulting from this PCN:</b>																
<table border="1"> <thead> <tr> <th>Assembly Site</th> <th>Assembly Site Origin (22L)</th> <th>ASO:</th> </tr> </thead> <tbody> <tr> <td>TI-Malaysia</td> <td>Assembly Site Origin (22L)</td> <td>ASO: MLA</td> </tr> <tr> <td><b>ASES</b></td> <td>Assembly Site Origin (22L)</td> <td>ASO: <b>ASH</b></td> </tr> </tbody> </table>					Assembly Site	Assembly Site Origin (22L)	ASO:	TI-Malaysia	Assembly Site Origin (22L)	ASO: MLA	<b>ASES</b>	Assembly Site Origin (22L)	ASO: <b>ASH</b>			
Assembly Site	Assembly Site Origin (22L)	ASO:														
TI-Malaysia	Assembly Site Origin (22L)	ASO: MLA														
<b>ASES</b>	Assembly Site Origin (22L)	ASO: <b>ASH</b>														

Sample product shipping label (not actual product label)


  
**TEXAS INSTRUMENTS**
  
 MADE IN: Malaysia
   
 2DC: 2D:
   

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

  
 OPT:
   
 ITEM: 39
   
**LBL: 5A (L)T0:1750**



(1P) SN74LS07NSR
   
 (Q) 2000 (D) 0336
   
 (31T) LOT: 3959047MLA
   
 (4W) TKY (1T) 7523483SI2
   
 (P)
   
 (2P) REV: (V) 0033317
   
 (20L) CSO: SHE (21L) CCO:USA
   
 (22L) ASO: MLA (23L) ACO: MYS

**Product Affected:**

TMP1075DR

## Qualification Report

Approve Date 20-Dec-2018

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TMP1075D	QBS Product Reference: TMP1075DGKT	QBS Package Reference: TLIN2029DQ1
HTOL	Life Test, 150C	300 Hours	-	3/231/0	
HAST	Biased HAST, 130C/85%RH	96 Hours	1/77/0	-	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	1/77/0	-	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	1/77/0	-	3/231/0
HTSL	High Temp Storage Bake 170C	420 Hours	1/77/0	-	-
HBM	ESD - HBM	4000V	-	1/3/0	-
CDM	ESD - CDM	1500 V	1/3/0	-	-
LU	Latch-up	(per JESD78)	-	1/6/0	
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	-	-
WBP	Bond Pull	Wires	1/76/0	-	-
WBS	Ball Bond Shear	Wires	1/76/0	-	-

- QBS: Qual By Similarity
- Qual Device TMP1075D is qualified at LEVEL1-260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Green/Pb-free Status:**

Qualified Pb-Free(SMT) and Green

THIS INFORMATION RELATING TO QUALITY AND RELIABILITY IS PROVIDED "AS IS." Product information detailed in this report may not accurately reflect TI's current product materials, processes and testing used in the construction of the TI products. Customers are solely responsible to conduct sufficient engineering and additional qualification testing to determine whether a device is suitable for use in their applications. Using TI products outside limits stated in TI's datasheet may void TI's warranty. See TI's Terms of Sale at "<http://www.ti.com/lscds/ti/legal/termsofsale.page>"

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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